

PMP10691 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPC8?	1		PMP7935	Any	PMP7935	N/A
C1, C2, C3, C4, C5, C6, C7, C8	8	10uF	GRM31CR61E106KA12L	MuRata	CAP, CERM, 10uF, 25V, +/-10%, X5R, 1206	1206
C9, C25, C41	3	100pF	GRM1555C1H101JA01D	MuRata	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0402	0402
C10, C23, C40	3	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	0402
C11, C12, C13, C14, C15, C16, C17, C18, C19, C20, C21, C26, C27, C28, C29, C30, C31, C32, C33, C34, C35, C36	22	100uF	GRM31CR60J107ME39L	MuRata	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1206	1206
C22	1	0.047uF	GRM155R71C473KA01D	MuRata	CAP, CERM, 0.047uF, 16V, +/-10%, X7R, 0402	0402
C24	1	680pF	C1608C0G1H681J	TDK	CAP, CERM, 680pF, 50V, +/-5%, C0G/NP0, 0603	0603
C37	1	3300pF	GRM155R71H332KA01D	MuRata	CAP, CERM, 3300pF, 50V, +/-10%, X7R, 0402	0402
C38	1	6800pF	GRM155R71E682KA01D	MuRata	CAP, CERM, 6800pF, 25V, +/-10%, X7R, 0402	0402
C39	1	4.7uF	GRM155R60J475ME87D	MuRata	CAP, CERM, 4.7uF, 6.3V, +/-20%, X5R, 0402	0402
C42	1	2.2uF	GRM188R61C225KE15D	MuRata	CAP, CERM, 2.2uF, 16V, +/-10%, X5R, 0603	0603
D1	1	0.55V	SDM20U40-7-F	Diodes Inc.	Diode, Schottky, 40V, 0.25A, SOD-523	SOD-523
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
J1	1	2x1	1715721	Phoenix Contact	Conn Term Block, 2POS, 5.08mm PCB	PhoenixContact_1715721
J2, J3	2	50 ohm	A-1JB	Amphenol	Connector, RF Jack, Vertical, Gold, SMD	A-1JB
L1	1	0.25uH	744301025	Würth Elektronik eiSos	Inductor, MnZn Ferrite, WE-HCM, 0.25uH, 40A, 0.00032 ohm, SMD	WE-HCM-1190
LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
Q1, Q2	2		CSD87350Q5D	Texas Instruments	NexFET Power Block, 30V, 40A, SON 5mm x 6mm	
Q3	1	0.2V	MMBT3904	Diodes Inc.	Transistor, NPN, 40V, 0.2A, SOT-523	SOT-523
R1, R2	2	6.81k	CRCW04026K81FKED	Vishay-Dale	RES, 6.81k ohm, 1%, 0.063W, 0402	0402
R3	1	2.15k	CRCW04022K15FKED	Vishay-Dale	RES, 2.15k ohm, 1%, 0.063W, 0402	0402
R4	1	100	CRCW0402100RFKED	Vishay-Dale	RES, 100 ohm, 1%, 0.063W, 0402	0402
R5	1	3.01k	CRCW04023K01FKED	Vishay-Dale	RES, 3.01k ohm, 1%, 0.063W, 0402	0402
R6	1	665	CRCW0402665RFKED	Vishay-Dale	RES, 665, 1%, 0.063 W, 0402	0402
R7	1	1.50k	CRCW04021K50FKED	Vishay-Dale	RES, 1.50k ohm, 1%, 0.063W, 0402	0402
R8	1	2.2	CRCW08052R20JNEA	Vishay-Dale	RES, 2.2 ohm, 5%, 0.125W, 0805	0805
R9	1	19.6k	CRCW040219K6FKED	Vishay-Dale	RES, 19.6k ohm, 1%, 0.063W, 0402	0402
R10	1	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0 ohm, 1%, 0.063W, 0402	0402
R11	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0k ohm, 1%, 0.063W, 0402	0402
R12	1	47.5k	CRCW040247K5FKED	Vishay-Dale	RES, 47.5k ohm, 1%, 0.063W, 0402	0402
R13	1	10k	CRCW040210K0JNED	Vishay-Dale	RES, 10k ohm, 5%, 0.063W, 0402	0402
R14	1	82.5k	CRCW040282K5FKED	Vishay-Dale	RES, 82.5k ohm, 1%, 0.063W, 0402	0402
R15	1	2.2	CRCW04022R20JNED	Vishay-Dale	RES, 2.2 ohm, 5%, 0.063W, 0402	0402
R16, R17	2	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9 ohm, 1%, 0.1W, 0603	0603
T1, T2	2	50A	CB35-36-CY	Panduit	Terminal 50A Lug	CB35-36-CY
TP1, TP3, TP5, TP9	4	Triple	1598-2	Keystone	Terminal, Turret, TH, Triple	Keystone1598-2
TP2, TP6	2	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
TP4, TP8, TP10, TP12, TP14	5	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
TP7, TP11, TP13	3	White	5002	Keystone	Test Point, TH, Miniature, White	Keystone5002
U1	1		LM27403RTW	Texas Instruments	Synchronous Buck Controller with Temperature Compensated, RTW0024C	RTW0024C
FID1, FID2, FID3, FID4, FID5, FID6	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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